METHOD OF PROTECTING SEMICONDUCTOR WAFER AND ADHESIVE FILM FOR PROTECTION OF SEMICONDUCTOR WAFER

ABSTRACT

The present invention is to provide a protecting method for a semiconductor wafer and an adhesive film for protection of a semiconductor wafer which makes it possible to straighten or avoid warpage in a semiconductor wafer and to prevent breakage of wafers during conveyance of wafers even if the thickness of a semiconductor wafer is thinned to approximately 150 μm or less.

The present invention provides a protecting method for a semiconductor wafer in a step of processing a semiconductor wafer comprising a first step of adhering an adhesive film for protection of a semiconductor wafer in which an adhesive layer is formed on one surface of a base film to a circuit-formed surface of the semiconductor wafer, a second step of heating the semiconductor wafer to which the adhesive film for protection of the semiconductor wafer is adhered, a third step of processing a non-circuit-formed surface of the semiconductor wafer by fixing the semiconductor wafer to which the adhesive film for protection of the semiconductor wafer is adhered on a grinding machine or an abrasive machine, and a fourth step of peeling the adhesive film for protection of the semiconductor wafer from the semiconductor wafer.